



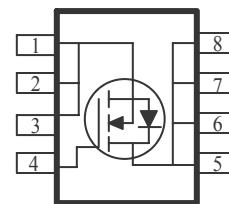
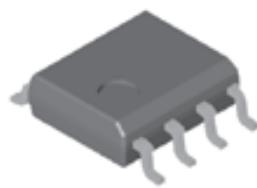
N-Channel 40-V (D-S) MOSFET

These miniature surface mount MOSFETs utilize a high cell density trench process to provide low $r_{DS(on)}$ and to ensure minimal power loss and heat dissipation. Typical applications are DC-DC converters and power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low $r_{DS(on)}$ provides higher efficiency and extends battery life
- Low thermal impedance copper leadframe SOIC-8 saves board space
- Fast switching speed
- High performance trench technology

PRODUCT SUMMARY

V_{DS} (V)	$r_{DS(on)}$ m(Ω)	I_D (A)
40	9 @ $V_{GS} = 10V$	23
	12 @ $V_{GS} = 4.5V$	20



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^{\circ}\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	20	
Continuous Drain Current ^a	I_D	23	A
		19	
Pulsed Drain Current ^b	I_{DM}	60	
Continuous Source Current (Diode Conduction) ^a	I_S	2.9	A
Power Dissipation ^a	P_D	3.1	W
		2.2	
Operating Junction and Storage Temperature Range	T_J, T_{Stg}	-55 to 150	$^{\circ}\text{C}$

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Maximum	Units
Maximum Junction-to-Ambient ^a	$R_{\theta JA}$	40	$^{\circ}\text{C}/\text{W}$
		80	$^{\circ}\text{C}/\text{W}$

Notes

- Surface Mounted on 1" x 1" FR4 Board.
- Pulse width limited by maximum junction temperature

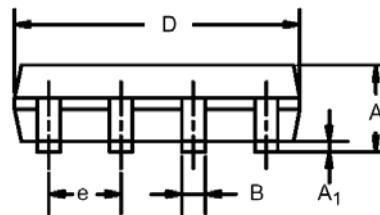
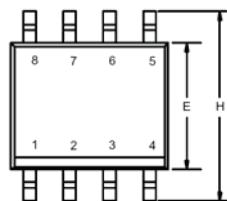
SPECIFICATIONS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Conditions	Limits			Unit
			Min	Typ	Max	
Static						
Gate-Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}$, $I_D = 250 \mu\text{A}$	1			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}$, $V_{GS} = 20 \text{ V}$			100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 24 \text{ V}$, $V_{GS} = 0 \text{ V}$			1	μA
		$V_{DS} = 24 \text{ V}$, $V_{GS} = 0 \text{ V}$, $T_J = 55^\circ\text{C}$			5	
On-State Drain Current ^A	$I_{D(\text{on})}$	$V_{DS} = 5 \text{ V}$, $V_{GS} = 10 \text{ V}$	30			A
Drain-Source On-Resistance ^A	$r_{DS(\text{on})}$	$V_{GS} = 10 \text{ V}$, $I_D = 23 \text{ A}$			9	$\text{m}\Omega$
		$V_{GS} = 4.5 \text{ V}$, $I_D = 20 \text{ A}$			12	
Forward Transconductance ^A	g_F	$V_{DS} = 15 \text{ V}$, $I_D = 23 \text{ A}$		90		S
Diode Forward Voltage	V_{SD}	$I_S = 2.3 \text{ A}$, $V_{GS} = 0 \text{ V}$		0.7		V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = 15 \text{ V}$, $V_{GS} = 4.5 \text{ V}$, $I_D = 23 \text{ A}$		25		nC
Gate-Source Charge	Q_{gs}			6		
Gate-Drain Charge	Q_{gd}			9		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 15 \text{ V}$, $R_L = 6 \Omega$, $I_D = 1 \text{ A}$, $V_{GEN} = 10 \text{ V}$		20		nS
Rise Time	t_r			13		
Turn-Off Delay Time	$t_{d(\text{off})}$			82		
Fall-Time	t_f			43		

Notes

- a. Pulse test: PW <= 300us duty cycle <= 2%.
- b. Guaranteed by design, not subject to production testing.

Package Information

SO-8: 8LEAD



Dim	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A₁	0.10	0.20	0.004	0.008
B	0.35	0.51	0.014	0.020
C	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°

